Description

The TLP281-4x series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a silicon planar phototransistor detector in a plastic SO16 package with different lead forming options. With the robust coplanar double mold structure, TLP281-4x series provide the most stable isolation feature.

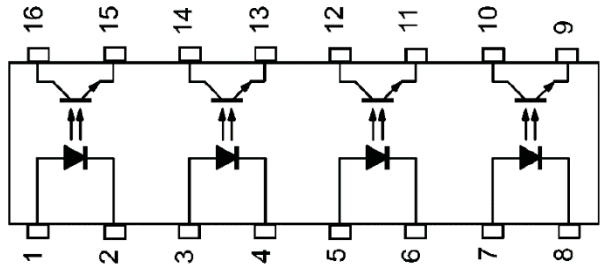
Features

- High isolation 3750 VRMS
- CTR flexibility available see order information
- DC input with transistor output
- Operating temperature range - 55 °C to 110 °C
- REACH compliance
- Halogen free
- MSL class 1

Applications

- Switch mode power supplies
- Programmable controllers
- Household appliances
- Office equipment

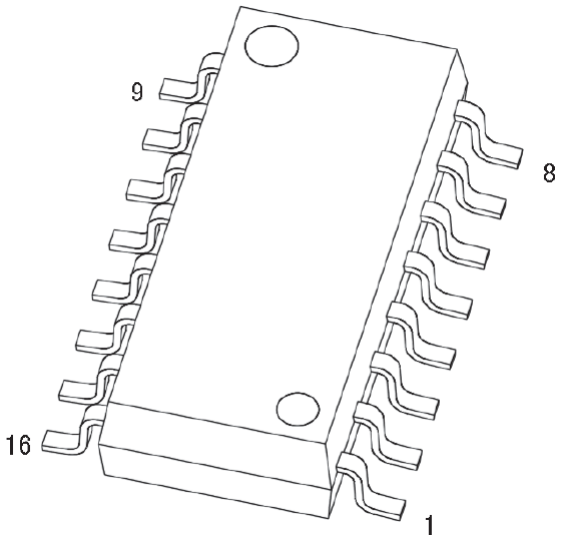
SCHEMATIC



PIN DEFINITION

1,3,5,7 : Anode
2,4,6,8 : Cathode
9,11,13,15: Emitter
10,12,14,16: Collector

PACKAGE OUTLINE



ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	VALUE	UNIT	NOTE
INPUT				
Forward Current	I_F	60	mA	
Peak Forward Current	I_{FP}	1	A	1
Reverse Voltage	V_R	6	V	
Input Power Dissipation	P_I	100	mW	
OUTPUT				
Collector - Emitter Voltage	V_{CEO}	80	V	
Emitter - Collector Voltage	V_{ECO}	7	V	
Collector Current	I_C	50	mA	
Output Power Dissipation	P_O	150	mW	
COMMON				
Total Power Dissipation	Ptot	200	mW	
Isolation Voltage	Viso	3750	Vrms	2
Operating Temperature	Topr	-55~110	°C	
Storage Temperature	Tstg	-55~125	°C	
Soldering Temperature	Tsol	260	°C	

Note 1. 100μs pulse, 100Hz frequency

Note 2. AC For 1 Minute, R.H. = 40 ~ 60%

ELECTRICAL OPTICAL CHARACTERISTICS at Ta=25°C							
PARAMETER	SYMBOL	MIN	TYP.	MAX.	UNIT	TEST CONDITION	NOTE
INPUT							
Forward Voltage	V_F	-	-	1.4	V	IF=10mA	
Reverse Current	I_R	-	-	10	μA	VR=6V	
Input Capacitance	Cin	-	10	-	pF	V=0, f=1kHz	
OUTPUT							
Collector Dark Current	I_{CEO}	-	-	100	nA	VCE=20V, IF=0	
Collector-Emitter Breakdown Voltage	BV_{CEO}	80	-	-	V	IC=0.1mA, IF=0	
Emitter-Collector Breakdown Voltage	BV_{ECO}	7	-	-	V	IE=0.1mA, IF=0	
TRANSFER CHARACTERISTICS							
Current Transfer Ratio	TLP281-4GB	CTR	100	-	600	%	IF=5mA, VCE=5V
	TLP281-4		50	-	600		
Collector-Emitter Saturation Voltage		$V_{CE(sat)}$	-	0.1	0.2	V	IF=10mA, IC=1mA
Isolation Resistance		R_{ISO}	10^12	10^14	-	Ω	DC500V, 40 ~ 60% R.H.
Floating Capacitance		C_{IO}	-	0.4	1	pF	V=0, f=1MHz
Response Time (Rise)		tr	-	3	18	μs	VCE=2V, IC=2mA RL=100Ω 3
Response Time (Fall)		tf	-	4	18	μs	3
Cut-off Frequency		fc	-	80	-	kHz	VCE=2V, IC=2mA RL=100Ω,-3dB 4

Note 3. Fig.12&13

Note 4. Fig.14

CHARACTERISTIC CURVES

Fig.1 Forward Current vs. Ambient Temperature

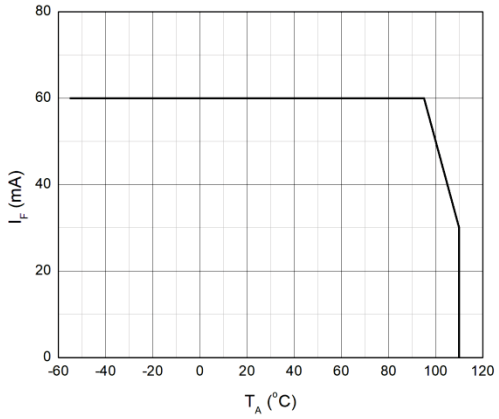


Fig.2 Collector Power Dissipation vs. Ambient Temperature

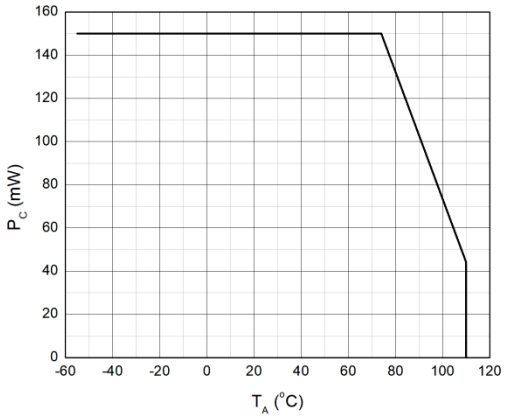


Fig.3 Forward Current vs. Forward Voltage

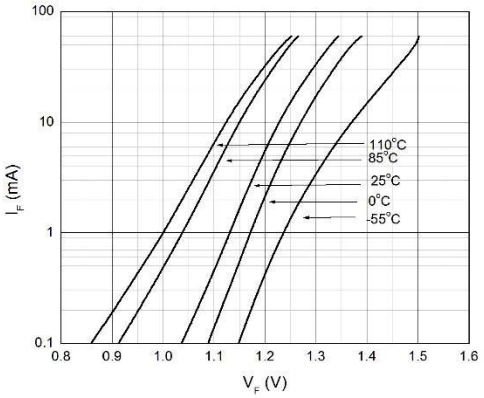


Fig.4 Collector Dark Current vs. Ambient Temperature

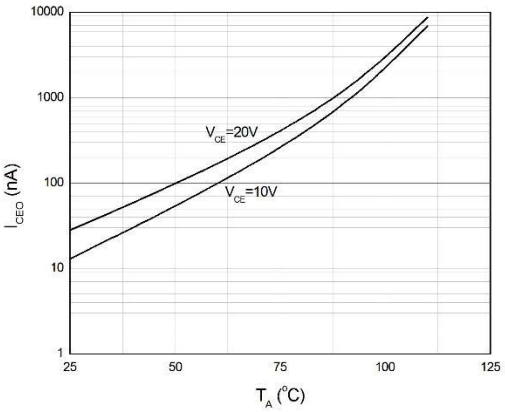


Fig.5 Collector Current vs. Collector-emitter Voltage

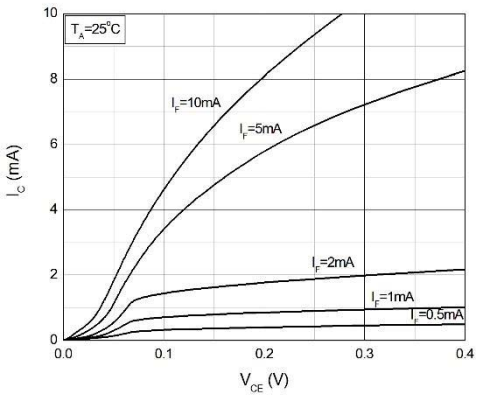
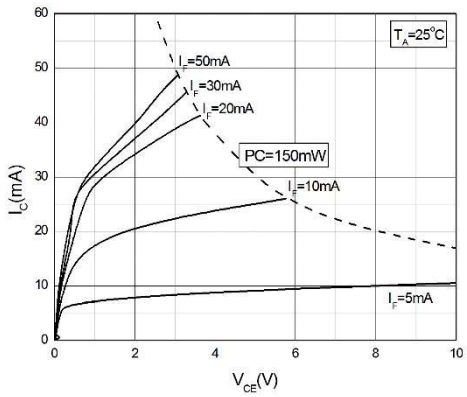


Fig.6 Collector Current vs. Collector-emitter Voltage



CHARACTERISTIC CURVES

Fig.7 Normalized Current Transfer Ratio vs. Forward Current

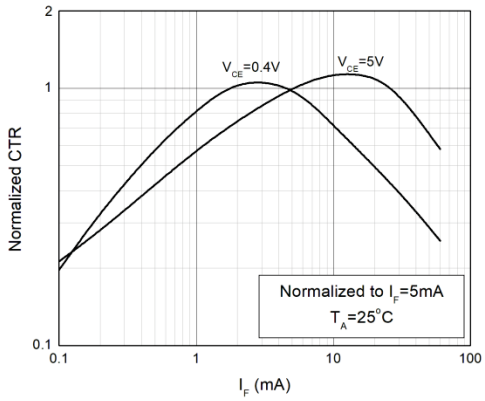


Fig.8 Normalized Current Transfer Ratio vs. Ambient Temperature

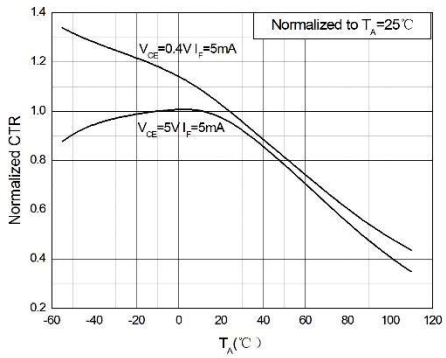


Fig.9 Collector-emitter Saturation Voltage vs. Ambient Temperature

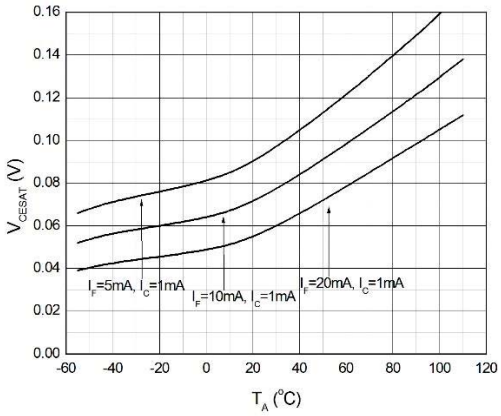


Fig.10 Switching Time vs. Load Resistance

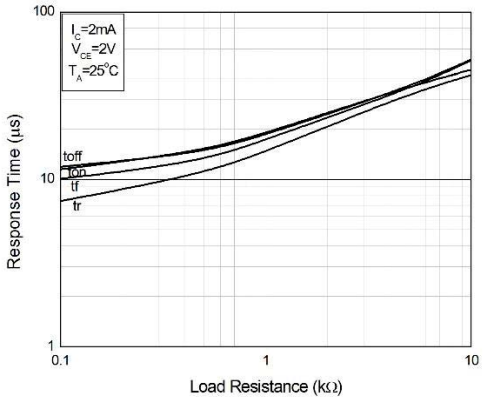
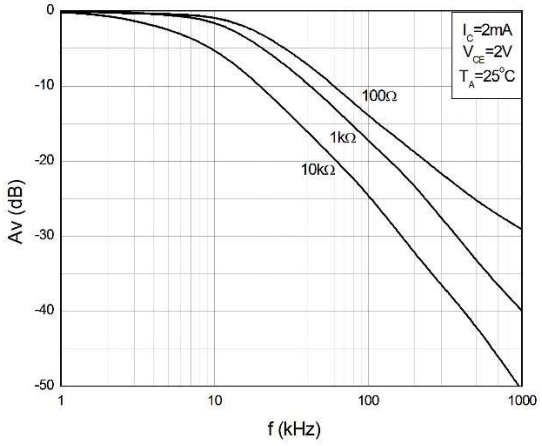


Fig.11 Frequency Response



TEST CIRCUITS

Fig.12 Test Circuits of Response Time

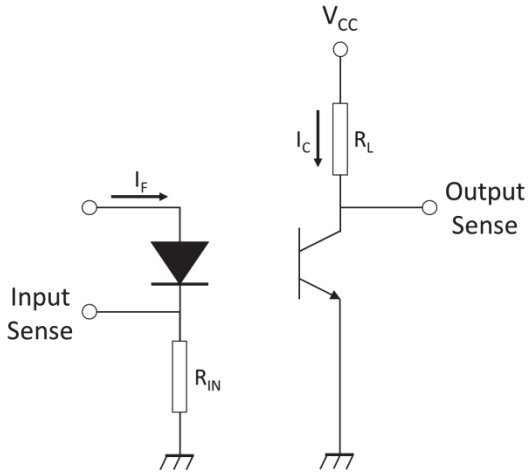


Fig.13 Curves of Response Time

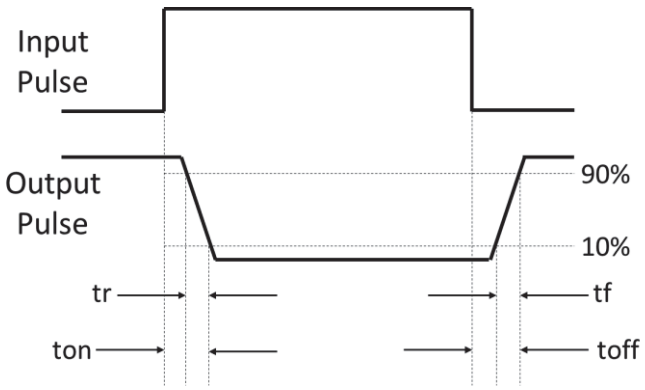
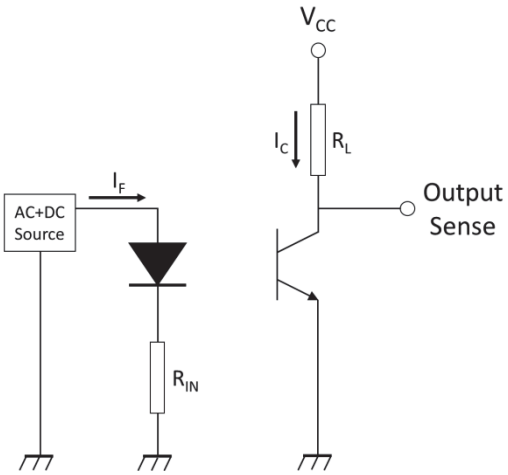
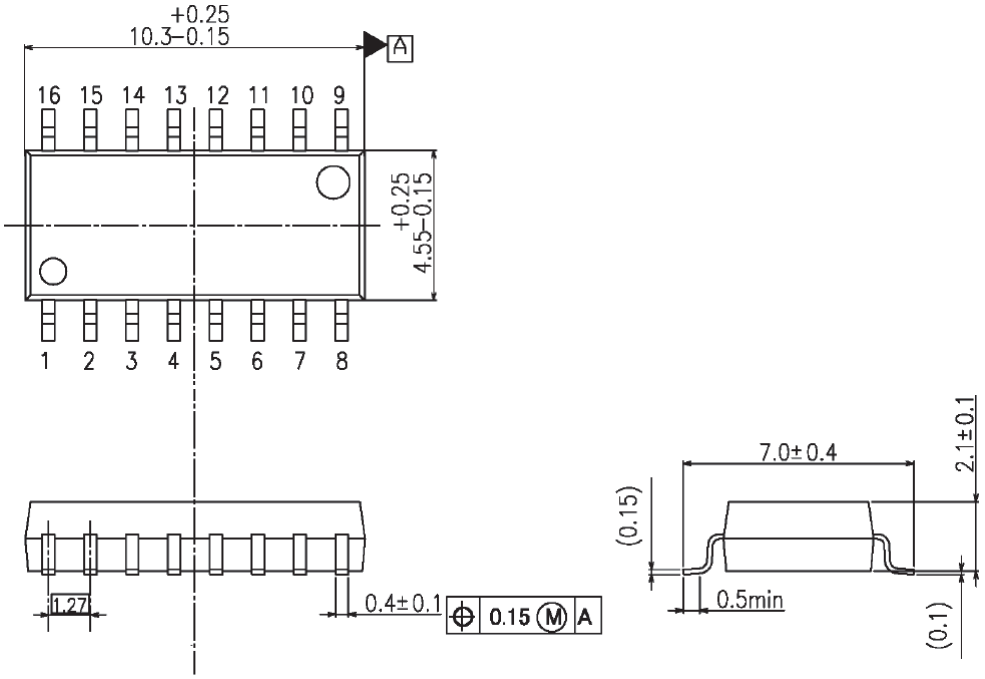


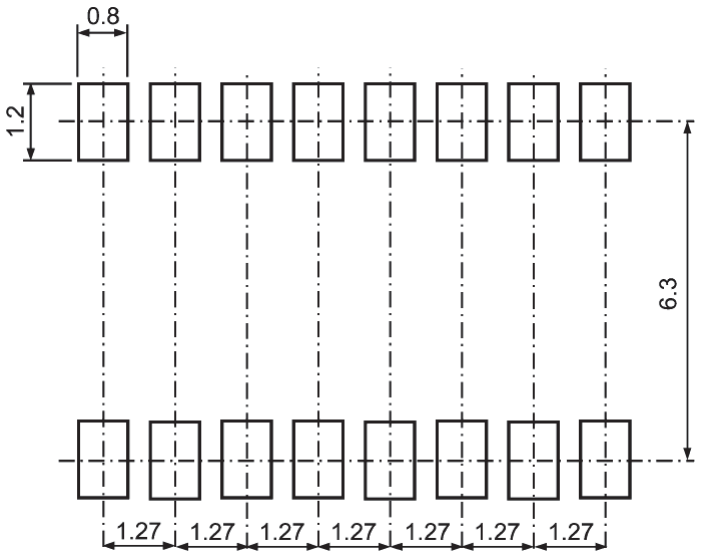
Fig.14 Test Circuits of Frequency Response



PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated)

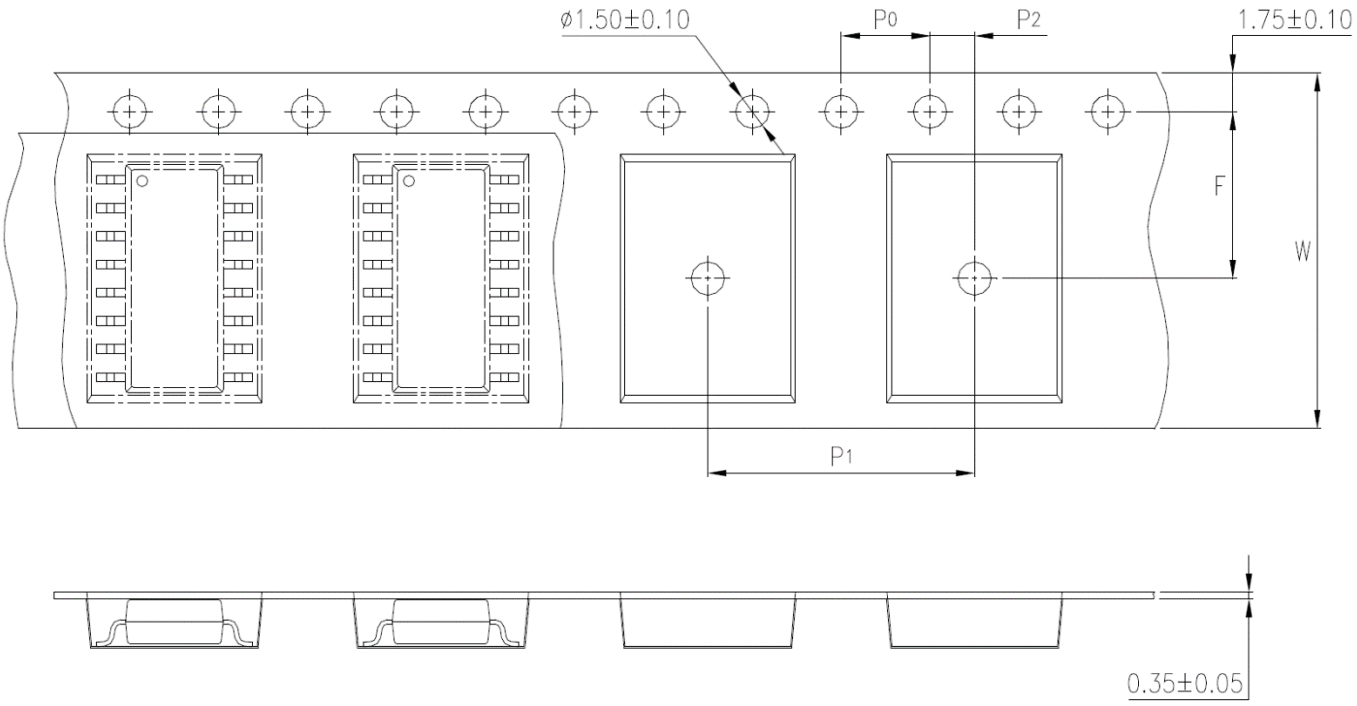


Recommended Solder Mask (Dimensions in mm unless otherwise stated)



CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option T1



Description	Symbol	Dimension mm (inch)
Tape Width	W	16 ± 0.3 (0.63)
Pitch of Sprocket Holes	P_0	4 ± 0.1 (0.15)
Distance of Compartment to Sprocket Holes	F	7.5 ± 0.1 (0.295)
	P_2	2 ± 0.1 (0.079)
Distance of Compartment to Compartment	P_1	12 ± 0.1 (0.47)

ORDERING AND MARKING INFORMATION

MARKING INFORMATION

TLP281-4X：Part Number
***1*：ISOCOM LIMITED**
Y: denotes 2 digit Year code
WW: denotes 2 digit Week code

ORDERING INFORMATION

TLP281-4x

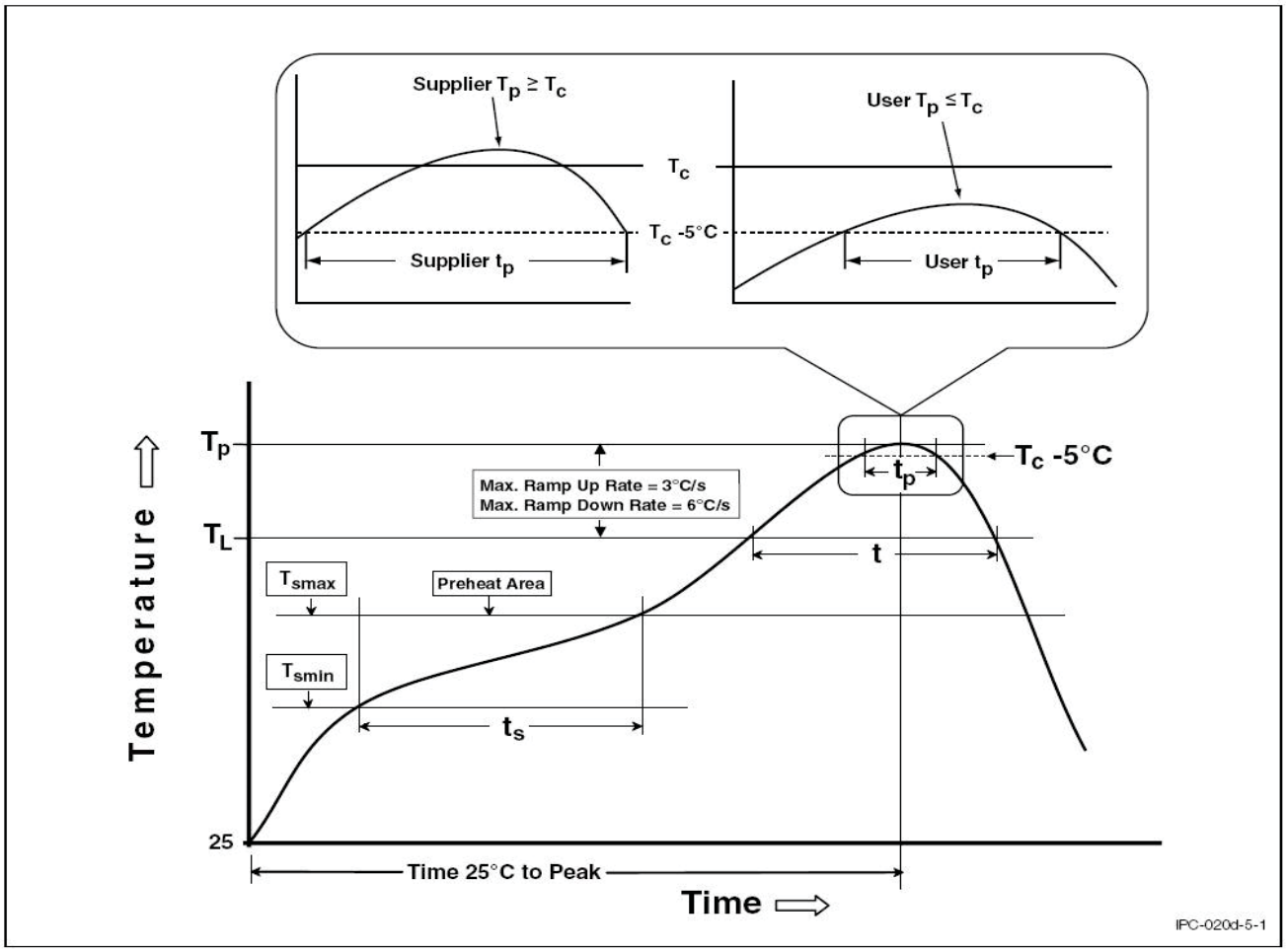
TLP – Company Abbr.
281-4 – Part Number
X – CTR Rank (GB/None)

PACKING QUANTITY

Option	Quantity	Quantity – Inner box	Quantity – Outer box
T1	2000 Units/Reel	1 Reels/Inner box	5 Inner box/Outer box = 10k Units

REFLOW INFORMATION

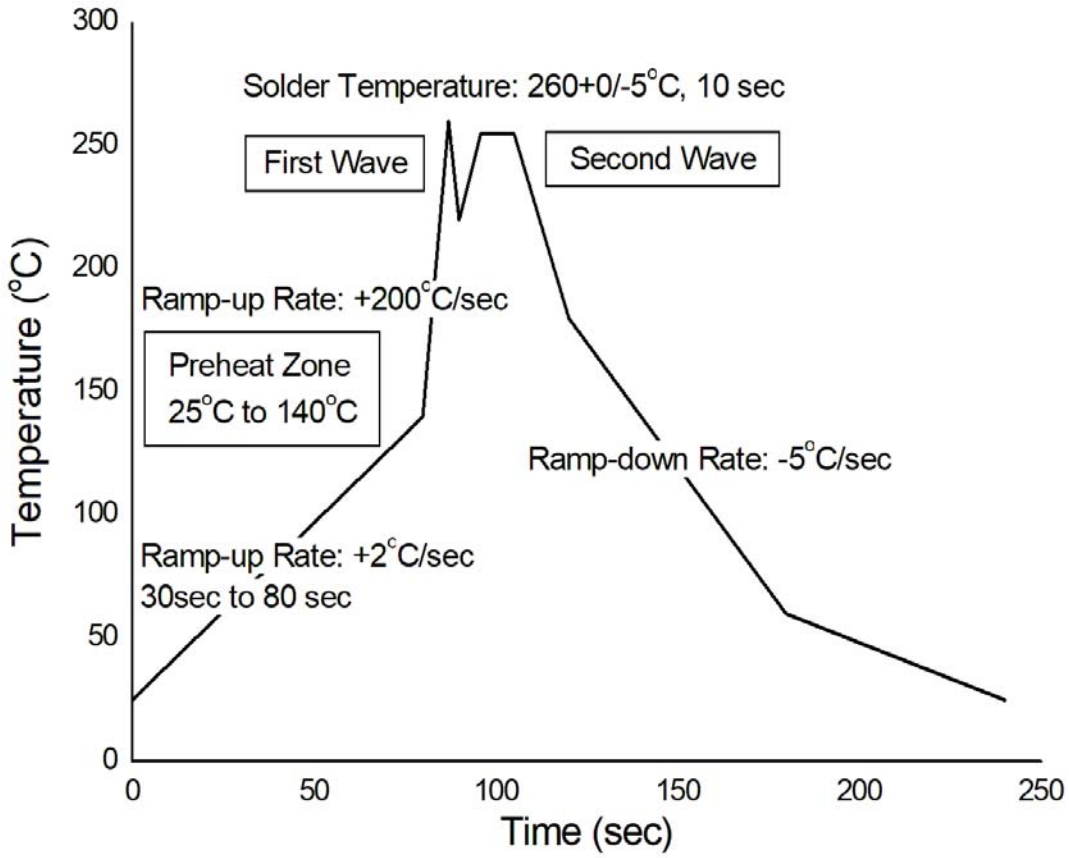
REFLOW PROFILE



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	100	150°C
Temperature Max. (Tsmax)	150	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3°C/second max.	3°C/second max.
Liquidous Temperature (TL)	183°C	217°C
Time (tL) Maintained Above (TL)	60 – 150 seconds	60 – 150 seconds
Peak Body Package Temperature	235°C +0°C / -5°C	260°C +0°C / -5°C
Time (tP) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (TP to TL)	6°C/second max	6°C/second max
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

TEMPERATURE PROFILE OF SOLDERING

WAVE SOLDERING (JESD22-A111 COMPLIANT)



HAND SOLDERING BY SOLDERING IRON	
Soldering Temperature	380+0/-5°C
Soldering Time	3 sec max.

- One time soldering is recommended for all soldering method.
- Do not solder more than three times for IR reflow soldering.

DISCLAIMER

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- The characteristic curves shown in this datasheet are representing typical performance which are not guaranteed.
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- Please contact ISOCOM LIMITED sales agent for special application request.
- Immerge unit’s body in solder paste is not recommended.
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